

TRIBO

HIGH-SPEED

CMP

SYSTEM



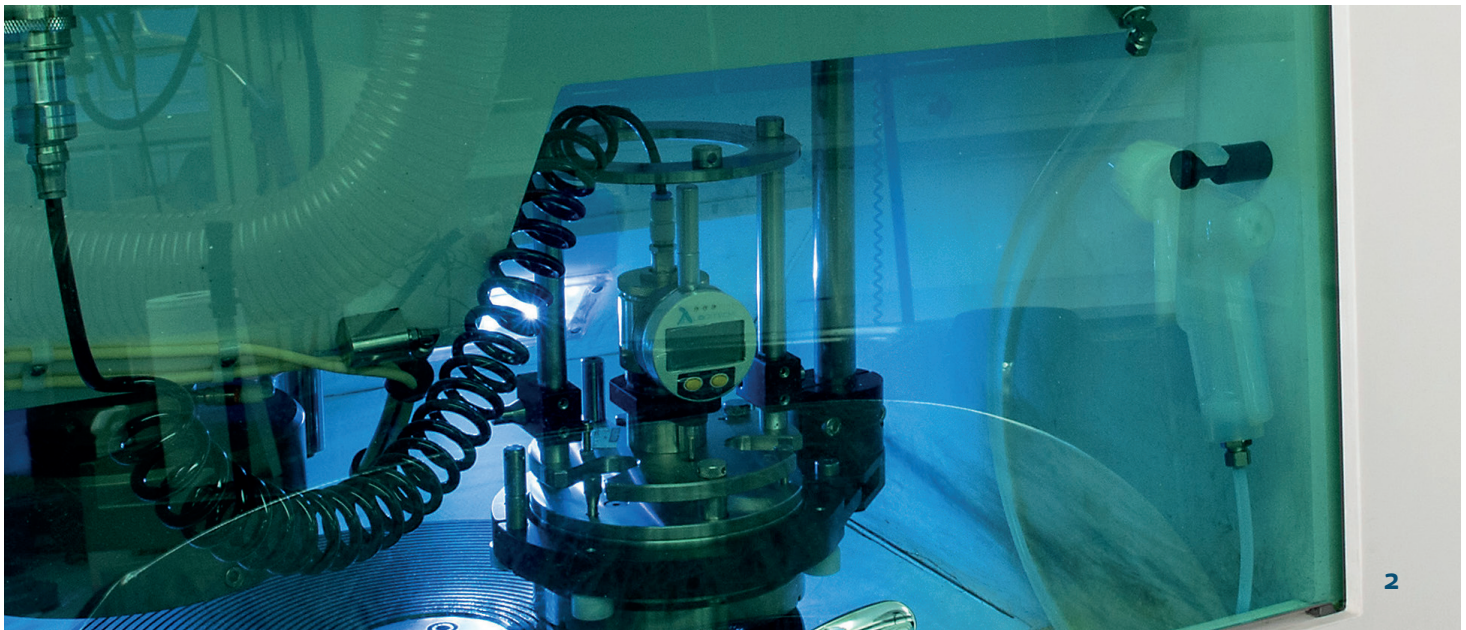
High-speed lapping and polishing system, processing and analysis of hard materials

Tribo High-Speed CMP System

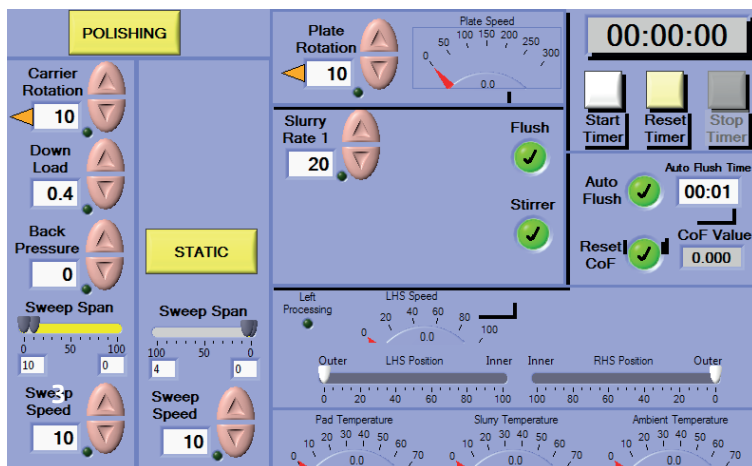
The Tribo High-Speed CMP is a Chemical Mechanical Polishing (CMP) system offering flexible and reliable processing and analysis of hard materials such as Gallium Nitride, Sapphire, Diamond, and Silicon Carbide. Designed for speed and versatility, the machine allows for quick and easy plate changes, with multiple polishing pad options. It is engineered to achieve the highest possible standards of processing control in laboratories with limited space, without sacrificing system performance.



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1: Tribo High Speed Precision Lapping & Polishing System

2: Processing of substrates, part wafers and full wafers up to 4"/100mm in diameter.

3: Process conditions controlled via the Graphical User Interface

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Key Features & Functionality

- The chemically resistant high speed system can process substrates, part wafers and full wafers up to 4"/100mm in diameter.
- For optimum results, the machine has been designed to work in combination with a Logitech Precision Lapping Jig system.
- The system carrier can apply high downloads to increase the polishing rate on harder materials, whilst the head back pressure can be used to adjust the sample shape.
- Plate speed can be set at any value from 0 to 300 rpm, according to the requirements of individual processes.
- Allows for a bespoke approach in machine set-up and operation by allowing the operator to configure a wide range of parameters and process conditions via the touch screen interface including CoF, carrier load and slurry delivery.
- The user interface on the high speed system utilises internationally accepted analytical software technology (Labview 10).
- Data can be taken from the in-situ process sensors and sub-systems and exported (via the USB port) to third party statistical or analytical software.

Technical Specifications

Wafer Capacity:	Up to 100mm/4"
Height	1150mm
Width	1380mm
Depth	985mm
Power Supply	220v - 240v Single inlet 16Amps - 50/60Hz
Plate Speed	0 - 300rpm
Plate Diameter	400mm
Carrier Speed	0 -100 rpm
Carrier back pressure	0 - 50psi / 344kPa
Carrier down pressure	0.4psi / 2.8kPa Max: load 9psi / 62kPa
Lapping jig chuck face diameter	11mm
Slurry flow rate	5-100ml/min
Machine weight	292kg



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